# imall

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Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



November 2008



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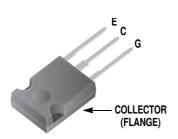
# FGH30N120FTD 1200V, 30A Trench IGBT

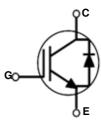
## **Features**

- · Field stop trench technology
- High speed switching
- Low saturation voltage: V<sub>CE(sat)</sub> = 1.6V @ I<sub>C</sub> = 30A
- High input impedance
- RoHS compliant •

# Applications

- Induction heating and Microwave oven
- · Soft switching applications





Using advanced field stop trench technology, Fairchild's 1200V trench IGBTs offer superior conduction and switching perfor-

mances, and easy parallel operation with exceptional avalanche

ruggedness. This device is designed for soft switching applica-

**General Description** 

tions.

### **Absolute Maximum Ratings**

Symbol	Description		Ratings	Units
V <sub>CES</sub>	Collector to Emitter Voltage		1200	V
V <sub>GES</sub>	Gate to Emitter Voltage		± 25	V
I <sub>C</sub>	Collector Current	@ T <sub>C</sub> = 25°C	60	A
	Collector Current	@ T <sub>C</sub> = 100°C	30	A
I <sub>CM (1)</sub>	Pulsed Collector Current	@ T <sub>C</sub> = 25 <sup>o</sup> C	90	A
I <sub>F</sub>	Diode Continuous Forward Current	@ T <sub>C</sub> = 100°C	30	A
P <sub>D</sub>	Maximum Power Dissipation	@ T <sub>C</sub> = 25°C	339	W
. D	Maximum Power Dissipation	@ T <sub>C</sub> = 100°C	132	W
TJ	Operating Junction Temperature	-55 to +150	°C	
T <sub>stg</sub>	Storage Temperature Range		-55 to +150	°C
TL	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 second	300	°C	

Notes: 1: Repetitive rating: Pulse width limited by max. junction temperature

## **Thermal Characteristics**

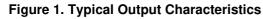
Symbol Parameter		Тур.	Max.	Units	
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction to Case	-	0.38	°C/W	
$R_{\theta JC}(Diode)$	Diode) Thermal Resistance, Junction to Case		1.2	°C/W	
$R_{\thetaJA}$	Thermal Resistance, Junction to Ambient	-	40	°C/W	

# Package Marking and Ordering Information

Device Marking Device Pa		Pa	ackage Reel Size		Таре	Tape Width		Quantity	
		ГО-247 -			-		30		
Electrica	al Cha	racteristics of t	the IC	<b>GBT</b> T <sub>C</sub> = 25	5°C unless otherwise noted	·			
Symbol	I Parameter			Test	Conditions	Min.	Тур.	Max.	Units
Off Charact	teristics								
BV <sub>CES</sub>	Collector	to Emitter Breakdown V	oltage	$V_{GE} = 0V, I_{C} = 250 \mu A$		1200	-	-	V
I <sub>CES</sub>	Collector	Cut-Off Current		$V_{CE} = V_{CES}, V_{GE} = 0V$		-	-	1	mA
I <sub>GES</sub>	G-E Leak	age Current		$V_{GE} = V_{GES}, V_{CE} = 0V$		-	-	±250	nA
On Charact	teristics								
V <sub>GE(th)</sub>	G-E Thre	shold Voltage		$I_{C} = 30 \text{mA}, V_{CE} = V_{GE}$		3.5	6	7.5	V
. /				I <sub>C</sub> = 30A, V <sub>G</sub>		-	1.6	2	V
V <sub>CE(sat)</sub>	Collector to Emitter Saturation Voltage		oltage	$I_{C} = 30A, V_{GE} = 15V,$ $T_{C} = 125^{\circ}C$		-	2.0	-	V
Dynamic C	haracteris	stics							
C <sub>ies</sub>	Input Cap	out Capacitance				-	5140	-	pF
C <sub>oes</sub>	Output Ca	apacitance		$ V_{CE} = 30V, V_{GE} = 0V, $ - f = 1MHz		-	150	-	pF
C <sub>res</sub>	Reverse <sup>-</sup>	Transfer Capacitance				-	95	-	pF
Switching (	Character	istics							
t <sub>d(on)</sub>		Delay Time				-	31	-	ns
t <sub>r</sub>	Rise Time	9				-	101	-	ns
t <sub>d(off)</sub>	Turn-Off	Delay Time		V <sub>CC</sub> = 600V,	lo = 30A	-	198	-	ns
t <sub>f</sub>	Fall Time			R <sub>G</sub> = 10Ω, V	′ <sub>GE</sub> = 15V,	-	259	-	ns
E <sub>on</sub>	Turn-On	Switching Loss		Resistive Lo	ad, T <sub>C</sub> = 25°C	-	0.54	-	mJ
E <sub>off</sub>		Switching Loss				-	1.16	1.51	mJ
E <sub>ts</sub>		tching Loss				-	1.70	-	mJ
t <sub>d(on)</sub>	Turn-On	Delay Time				-	40	-	ns
t <sub>r</sub>	Rise Time					-	127	-	ns
t <sub>d(off)</sub>	Turn-Off	Delay Time		$V_{CC} = 600V$ , $I_C = 30A$ , $R_G = 10\Omega$ , $V_{GE} = 15V$ , Resistive Load, $T_C = 125^{\circ}C$		-	211	-	ns
t <sub>f</sub>	Fall Time					-	364	-	ns
E <sub>on</sub>	Turn-On	Switching Loss				-	0.74	-	mJ
E <sub>off</sub>	Turn-Off	Switching Loss				-	1.63	-	mJ
E <sub>ts</sub>	Total Swit	tching Loss				-	2.37	-	mJ
Qg	Total Gate	e Charge				-	208	-	nC
Q <sub>ge</sub>	Gate to E	mitter Charge		$V_{CE} = 600V,$	I <sub>C</sub> = 30A,	-	41	-	nC
Q <sub>gc</sub>		Collector Charge		V <sub>GE</sub> = 15V		-	97	-	nC

Symbol	Parameter	Parameter Test Conditions		Min.	Тур.	Max	Units
V <sub>FM</sub>	Diode Forward Voltage	I <sub>F</sub> = 30A	$T_{\rm C} = 25^{\rm o}{\rm C}$	-	1.3	1.7	v
FIN	FM Diode Forward Voltage	1 <sub>F</sub> = 00/1	$T_{C} = 125^{\circ}C$	-	1.3	-	1
t <sub>rr</sub> Diode	Diode Reverse Recovery Time	- Ι <sub>F</sub> =30A, di/dt = 200A/μs	$T_{\rm C} = 25^{\rm o}{\rm C}$	-	730	-	ns
•rr	,		$T_{\rm C} = 125^{\rm o}{\rm C}$	-	775	-	
1			$T_{\rm C} = 25^{\rm o}{\rm C}$	-	43	-	А
Irr Diode Feak Nev			$T_{\rm C} = 125^{\rm o}{\rm C}$	-	47	-	~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~
0	Q <sub>rr</sub> Diode Reverse Recovery Charge		$T_{\rm C} = 25^{\rm o}{\rm C}$	-	5.9	-	μC
∽rr			T <sub>C</sub> = 125°C	-	18.2	-	μΟ

# **Typical Performance Characteristics**



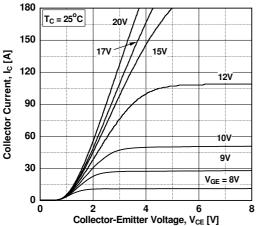


Figure 3. Typical Saturation Voltage Characteristics

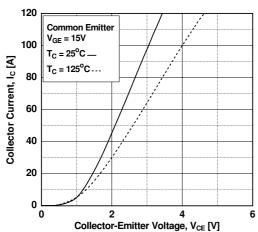


Figure 5. Saturation Voltage vs. Case Temperature at Variant Current Level

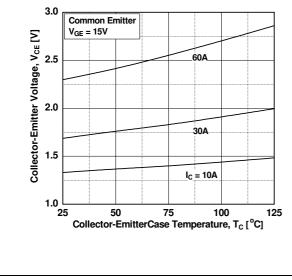


Figure 2. Typical Output Characteristics

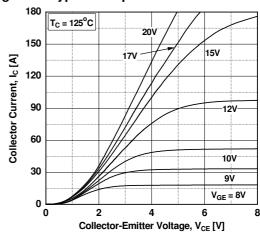


Figure 4. Transfer Characteristics

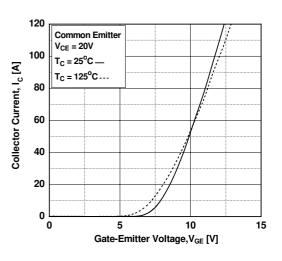
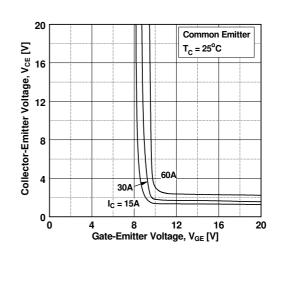


Figure 6. Saturation Voltage vs.  $V_{GE}$ 



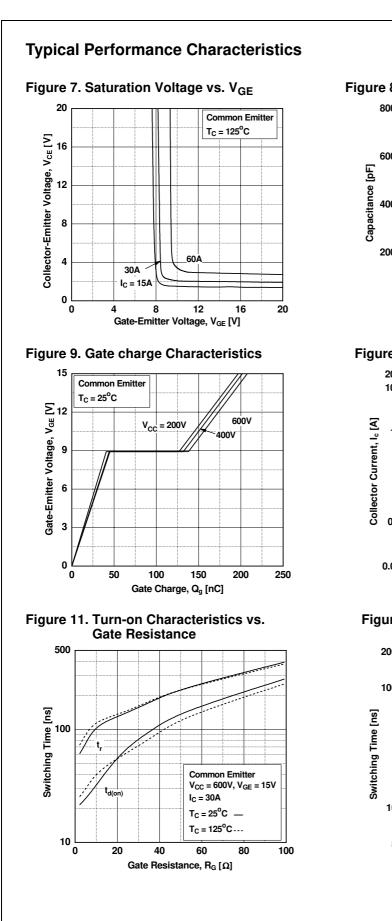


Figure 8. Capacitance Characteristics

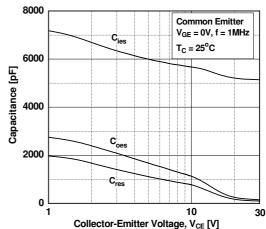


Figure 10. SOA Characteristics

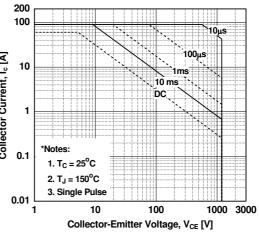
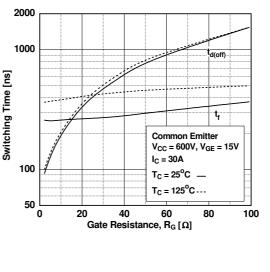
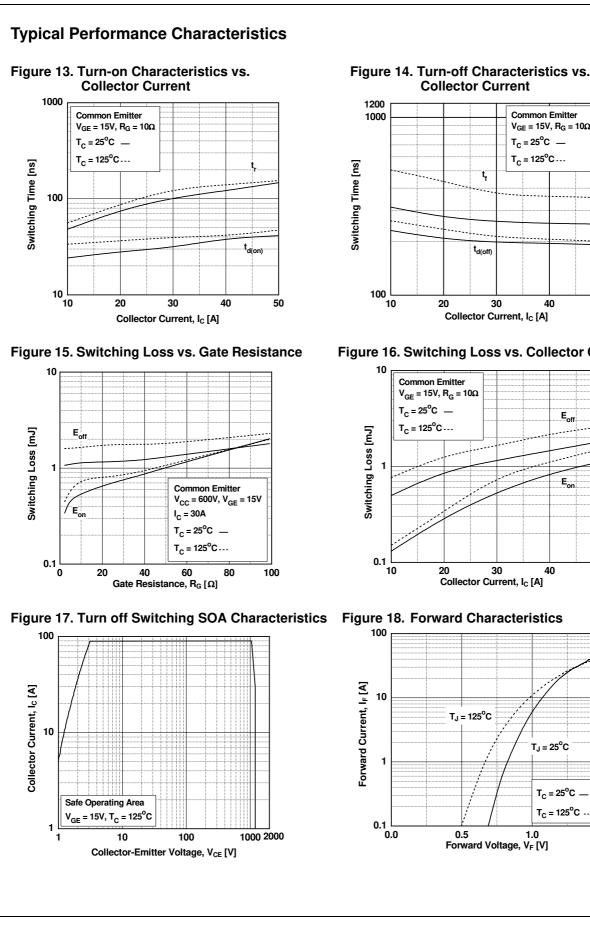
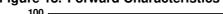


Figure 12. Turn-off Characteristics vs. Gate Resistance



FGH30N120FTD 1200V, 30A Trench IGBT



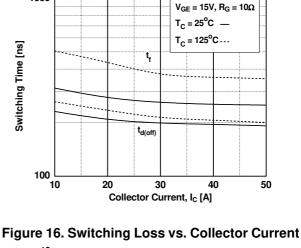


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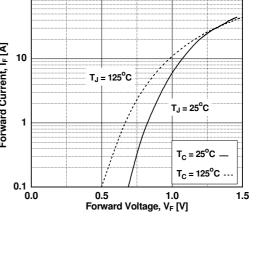
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Common Emitter

**Figure 18. Forward Characteristics** 



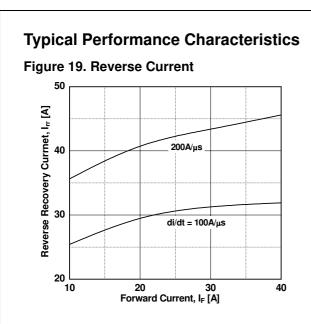
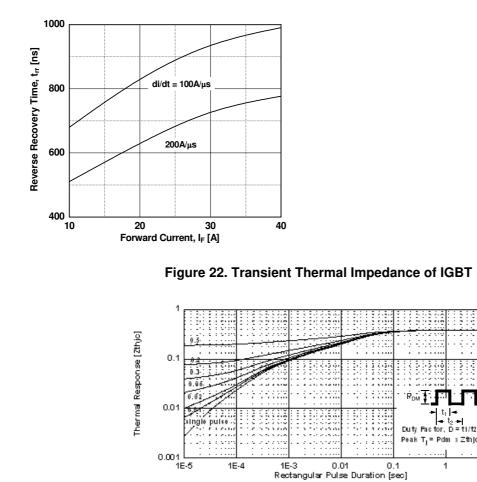
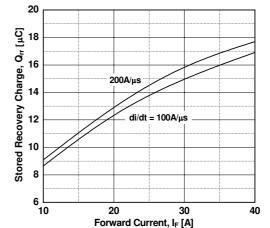


Figure 21. Reverse Recovery Time

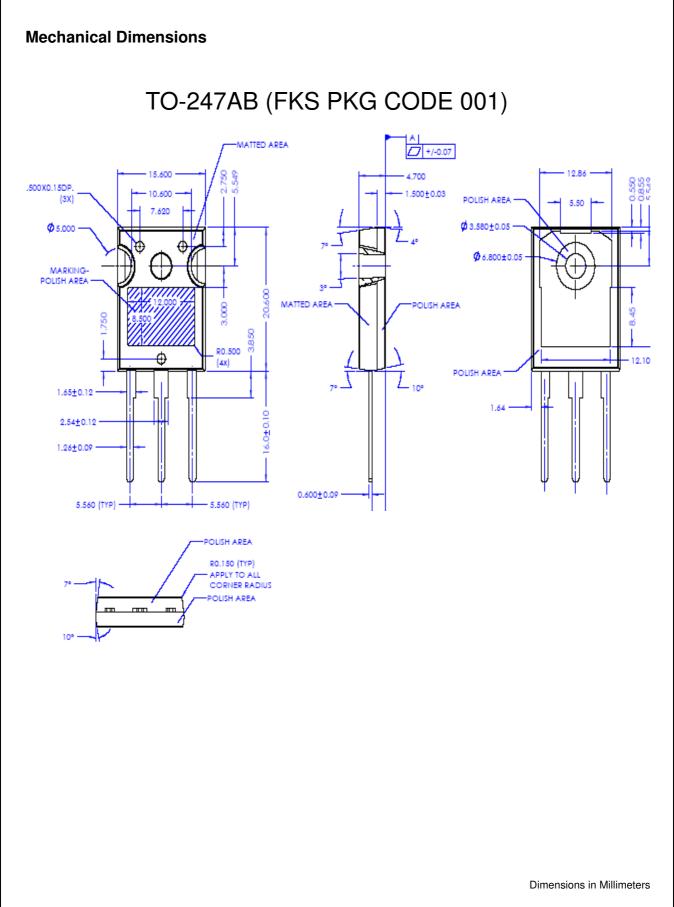






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